BASE
 EMITTER
 COLLECTOR

#### **Features**

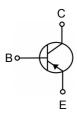
Driver Transistors



# Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MMBTA55	SOT-23	2H	3000





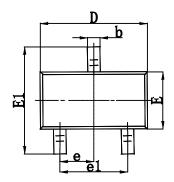
# Maxmim Ratings (Ta=25 unless otherwise noted)

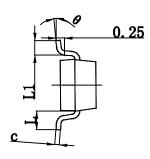
Symbol	Parameter	Value	Unit
V <sub>СВО</sub>	Collector-Base Voltage	-60	V
V <sub>CEO</sub>	Collector-Emitter Voltage	-60	V
V <sub>EBO</sub>	Emitter-Base Voltage	-4	V
Ic	Collector Current	-500	mA
Pc	Collector Power Dissipation	225	mW
R <sub>⊙JA</sub>	Thermal Resistance From Junction To Ambient	556	°CW
$T_J, T_stg$	Operation Junction and Storage Temperature Range	-55~+150	°C

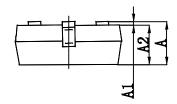
### Electrcal Charcteristics (Ta=25 unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	I <sub>C</sub> =-100μA, I <sub>E</sub> =0	-60			V
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> =-1mA, I <sub>B</sub> =0	-60			V
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	I <sub>E</sub> =-100μA, I <sub>C</sub> =0	-4			V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> =-60V, I <sub>E</sub> =0			-0.1	μΑ
Collector cut-off current	I <sub>CEO</sub>	V <sub>CE</sub> =-60V, I <sub>B</sub> =0			-0.1	μA
DC current gain	h <sub>FE(1)</sub>	V <sub>CE</sub> =-1V, I <sub>C</sub> =-10mA	100		400	
DC current gam	h <sub>FE(2)</sub>	V <sub>CE</sub> =-1V, I <sub>C</sub> =-100mA	100			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =-100mA, I <sub>B</sub> =-10mA			-0.25	V
Base-emitter voltage	$V_{BE}$	V <sub>CE</sub> =-1V, I <sub>C</sub> =-100mA			-1.2	V
Transition frequency	f⊤	V <sub>CE</sub> =-1V,I <sub>C</sub> =-100mA, f=100MHz	50			MHz

# **SOT-23 Package Outline Dimensions**

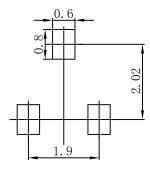






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

### **SOT-23 Suggested Pad Layout**



- 1.Controlling dimension:in millimeters. 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.



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